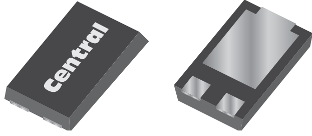
Material Composition Specification

TLM364 Case



Device average mass . . . . 92 mg
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	10.41%	9.58	Si	7440-21-3	10.41%	9.58	104,130
clip	Cu alloy	5.36%	4.93	Cu	7440-50-8	5.21%	4.79	52,065
				Fe	7439-89-6	0.15%	0.14	1,522
leadframe	Cu alloy	32.72%	30.1	Cu	7440-50-8	32.66%	30.05	326,630
				Fe	7439-89-6	0.05%	0.05	543
die attach	high temperature solder paste	4.52%	4.16	Pb	7439-92-1	4.18%	3.85	41,848
				Sn	7440-31-5	0.23%	0.21	2,283
				Ag	7440-22-4	0.11%	0.1	1,087
encapsulation*	EMC GREEN	46.98%	43.22	silica	60676-86-0	36.17%	33.28	361,739
				epoxy resin	29690-82-2	4.70%	4.32	46,957
				phenol resin	9003-35-4	4.55%	4.19	45,543
				carbon black	1333-86-4	0.14%	0.13	1,413
				metal hydroxide	1309-42-8	1.41%	1.3	14,130
plating	matte tin	0.01%	0.01	Sn	7440-31-5	0.01%	0.01	109

*EMC GREEN molding compound is Halogen Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.